

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau

(43) International Publication Date
26 June 2025 (26.06.2025)



(10) International Publication Number
WO 2025/136895 A1

(51) International Patent Classification:

C08G 77/04 (2006.01) C08F 297/04 (2006.01)
C08K 3/22 (2006.01)

(21) International Application Number:

PCT/US2024/060444

(22) International Filing Date:

17 December 2024 (17.12.2024)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

63/612,389 20 December 2023 (20.12.2023) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG,
KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY,
MA, MD, MG, MK, MN, MU, MW, MX, MY, MZ, NA,
NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO,
RS, RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH,
TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS,
ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, CV,
GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST,
SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ,
RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ,
DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT,
LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE,
SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, KM, ML, MR, NE, SN, TD, TG).

Published:

— with international search report (Art. 21(3))

(54) Title: SEMICONDUCTOR DEVICE AND METHODS OF MANUFACTURING A SEMICONDUCTOR DEVICE

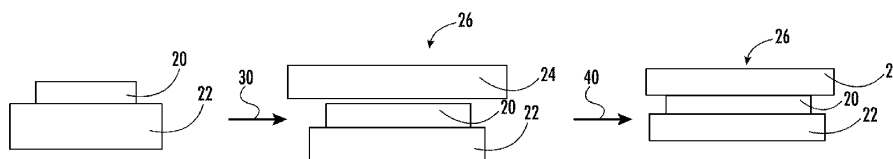


FIG. 1

(57) Abstract: A semiconductor device including a semiconductor chip formed from a semiconductive material and a cover formed from a conductive material is provided. The semiconductor chip and cover are bonded with a thermal interface material composition that includes metal particles dispersed in a resin or resin blend and a silane-based adhesion promoter. The TIM composition may also include a rubber and a curing agent. Methods of making semiconductor devices are also provided.



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